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AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph beginning on line 18 of page 3 as follows:

As an alternative and replacement to bond wires, die bumps are used in a die attachment known as the flip-chip method. However, the flip-chip method does not work well with MMICs that have been designed using conventional RF design and layout rules. Microwave structures such as micro-strips and strip-lines have ~~their~~ unique RF characteristics depending on their spacing~~[[,]]~~ and the media above and ground plane below them. Currently, there are only a few design and layout tools to support flip-chip mounted microwave devices under development.

Please amend the first full paragraph on page 8 as follows:

~~FIG. 4~~ The Figure illustrates a schematic cross-sectional view of a microwave package 100 consistent with the present invention, showing the construction and layer build-up of one semiconductor package.

Please amend the paragraph beginning on line 21 of page 8 as follows:

In one embodiment consistent with the present invention, a Silicon Carbide (SiC) sealant coating, or a SiC over Benzocyclobutene (BCB) (as an Interlayer Dielectric) sealant coating, (for example, Chip Seal™ made by Dow Corning) is disposed topside of the GaAs MMIC 102 to form a near-hermetic seal. The sealant used in the present invention is applied by a standard process technology, and is compatible with all current MCM interconnection approaches, including wire bond TAB, flip-chip, etc. The sealant may form a layer of approximately 4000 Angstroms on the MMIC 102, and is deposited directly on the passivation layers (0.5 μm/10_μm) on the topside of the MMIC 102. The near-hermetic passivation layers (0.5 μm/10_μm) on the topside of the MMIC 102 cover air bridges. The

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SiC coating will seal the microchips from inorganic and organic liquid and vapors.

Please amend the third full paragraph on page 11 as follows:

Finally, in one embodiment consistent with the present invention there is a non-metallic or metallized Liquid Crystal Polymer (LCP) cover 107, which may be ~~epoxied or solder attached in place, respectively,~~ attached with epoxy or solder and used to protect the device 100 from mechanical damage due to handling. The cover may be disposed on the conformal-coated MMIC.